

NCE P-Channel Super Trench Power MOSFET

Description

The NCEP15P30AG uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(on)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- $V_{DS} = -150V, I_D = -30A$
 $R_{DS(on)} = 85m\Omega$ (typical) @ $V_{GS} = -10V$
 $R_{DS(on)} = 103m\Omega$ (typical) @ $V_{GS} = -4.5V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 150 °C operating temperature
- Pb-free lead plating

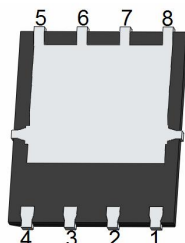
100% UIS TESTED!

100% ΔV_{DS} TESTED!

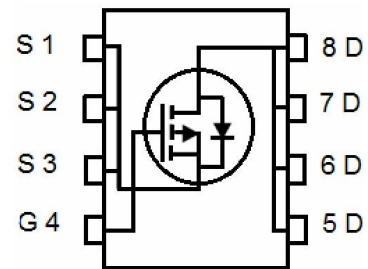
PDFN 5X6-8L



Top View



Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
P15P30AG	NCEP15P30AG	PDFN 5X6-8L	Ø330mm	12mm	5000units

Absolute Maximum Ratings ($T_c = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-150	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	-30	A
Drain Current-Continuous($T_c = 100^\circ\text{C}$)	$I_D(100^\circ\text{C})$	-21	A
Pulsed Drain Current	I_{DM}	-120	A
Maximum Power Dissipation	P_D	200	W
Derating factor		1.6	W/°C
Single pulse avalanche energy (Note 1)	E_{AS}	184	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.63	°C/W
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Electrical Characteristics (T_c=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-150	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-150V, V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.2	-1.7	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-15A	-	85	100	mΩ
		V _{GS} =-4.5V, I _D =-15A	-	103	115	mΩ
Forward Transconductance	g _{FS}	V _{DS} =-5V, I _D =-15A	-	30	-	S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =-75V, V _{GS} =0V, F=1.0MHz	-	1650	-	pF
Output Capacitance	C _{oss}		-	135	-	pF
Reverse Transfer Capacitance	C _{rss}		-	12	-	pF
Switching Characteristics <small>(Note 2)</small>						
Turn-on Delay Time	t _{d(on)}	V _{DD} =-50V, I _D =-15A V _{GS} =-10V, R _G =1.6Ω	-	10	-	nS
Turn-on Rise Time	t _r		-	18	-	nS
Turn-Off Delay Time	t _{d(off)}		-	20	-	nS
Turn-Off Fall Time	t _f		-	15	-	nS
Total Gate Charge	Q _g	V _{DS} =-75V, I _D =-15A, V _{GS} =-10V	-	25	-	nC
Gate-Source Charge	Q _{gs}		-	5.2	-	nC
Gate-Drain Charge	Q _{gd}		-	3.1	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-15A	-		-1.2	V
Diode Forward Current	I _S		-	-	-30	A
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F =-15A	-	55	-	nS
Reverse Recovery Charge	Q _{rr}	di/dt = 100A/μs	-	101	-	nC

Notes:

1. EAS condition : T_J=25°C, V_{DD}=-50V, V_G=-10V, L=0.5mH, R_G=25Ω
2. Guaranteed by design, not subject to production
3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_J(MAX)=150°C. The SOA curve provides a single pulse rating.

Typical Electrical and Thermal Characteristics

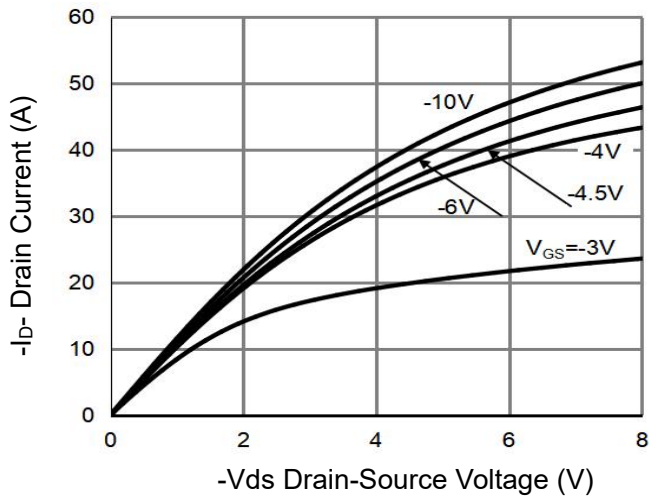


Figure 1 Output Characteristics

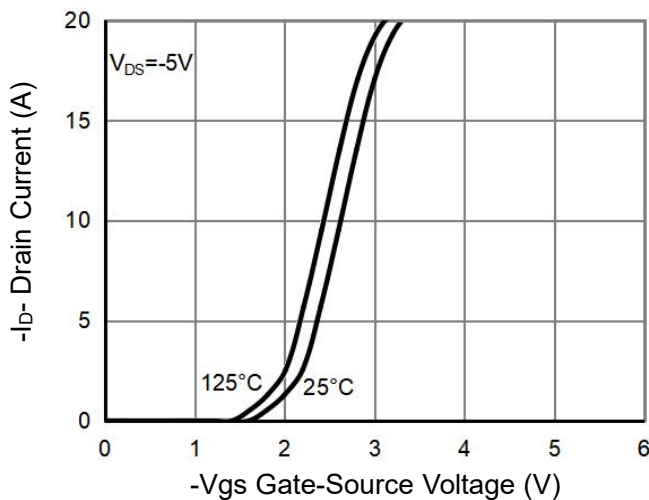


Figure 2 Transfer Characteristics

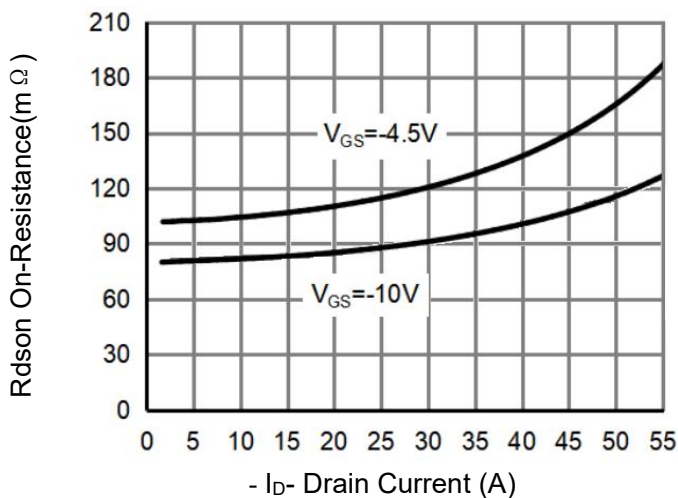


Figure 3 Rdson- Drain Current

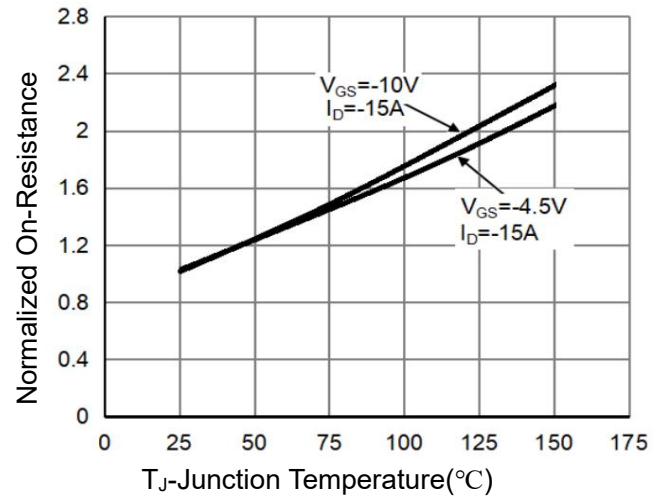


Figure 4 Rdson-Junction Temperature

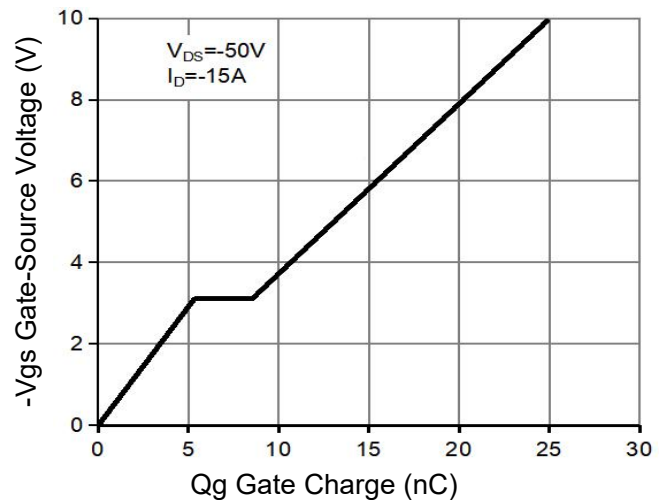


Figure 5 Gate Charge

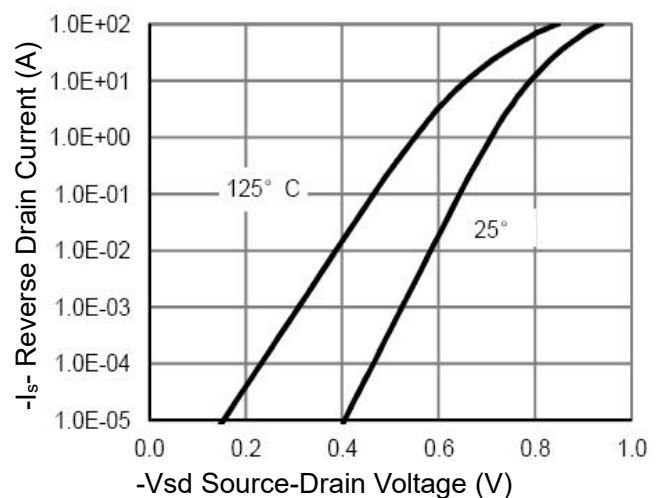


Figure 6 Source- Drain Diode Forward

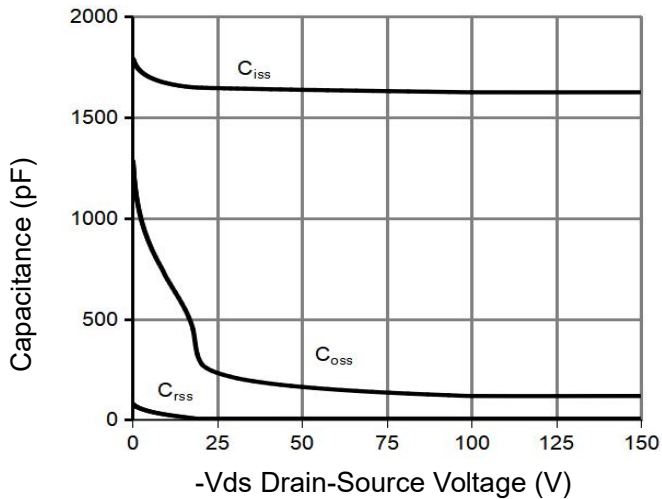


Figure 7 Capacitance vs Vds

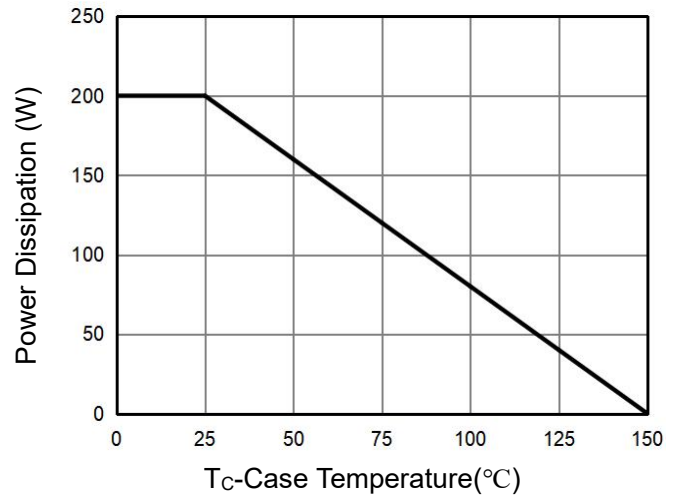


Figure 9 Power De-rating

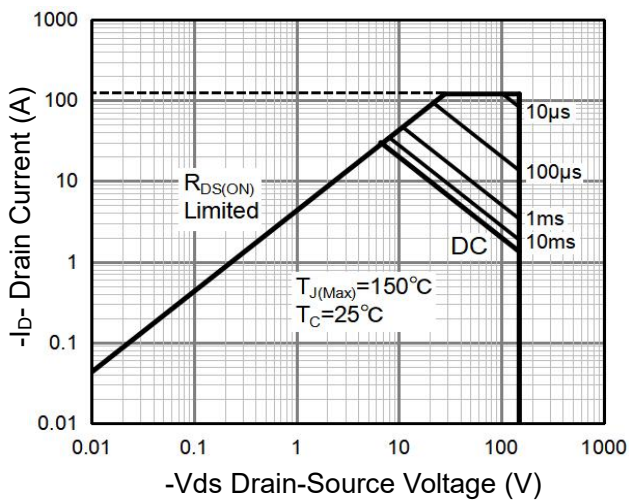


Figure 8 Safe Operation Area (Note 3)

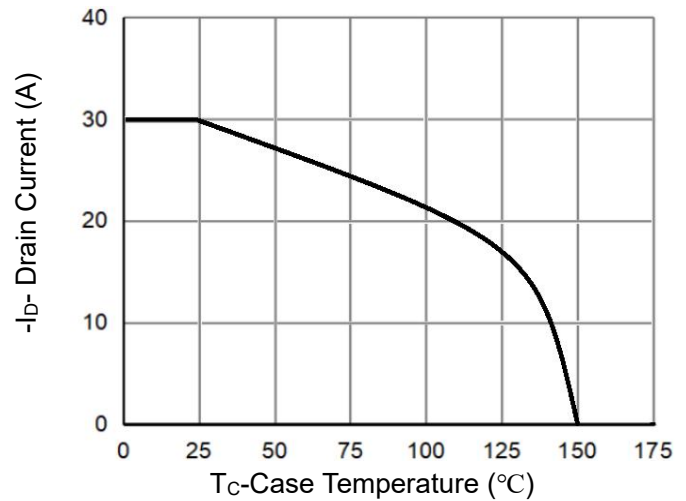


Figure 10 Current De-rating

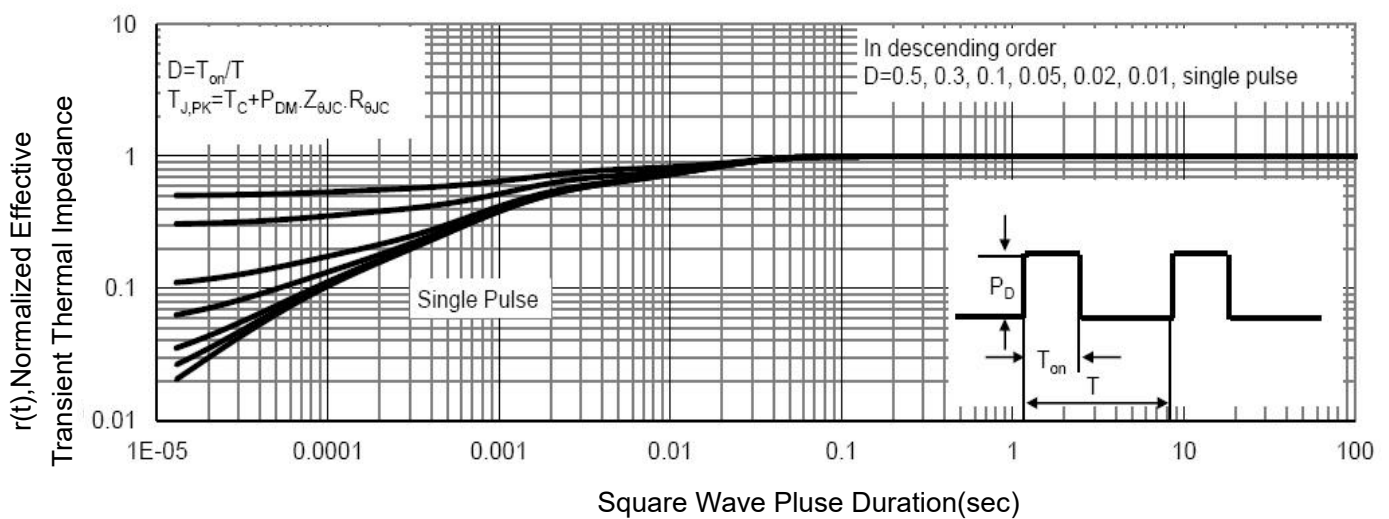
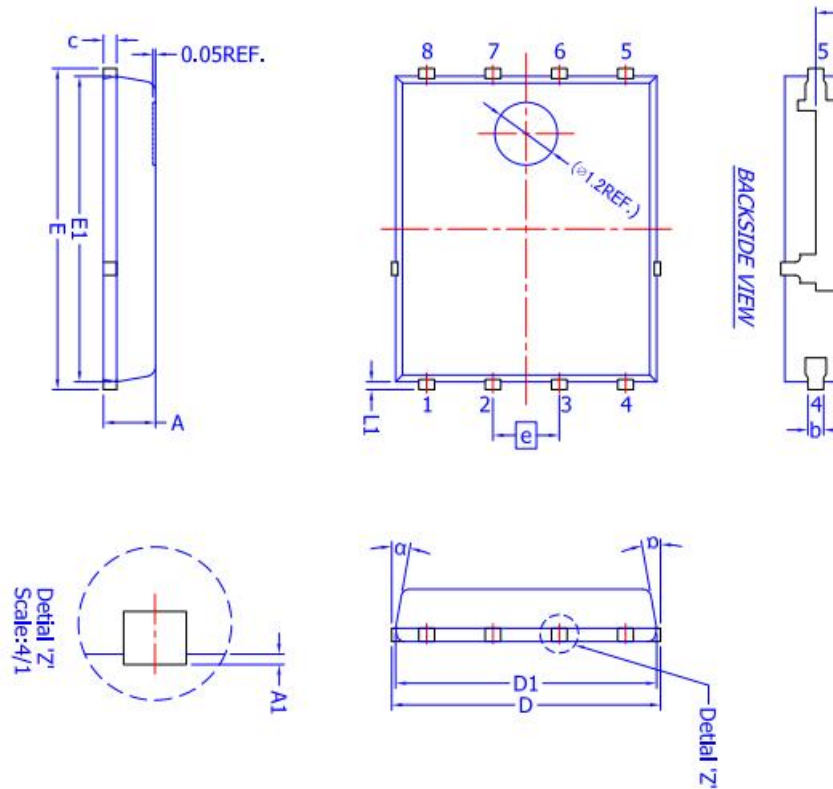


Figure 11 Normalized Maximum Transient Thermal Impedance

PDFN5X6-8L Package Information



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.30	0.40	0.50
c	0.20	0.25	0.30
D	5.15 BSC		
D1	5.00 BSC		
D2	3.76	3.81	3.86
E	6.15 BSC		
E1	5.80	5.85	5.90
E2	3.45	3.65	3.85
e	1.27 BSC		
H	0.51	0.61	0.71
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.08	0.15	0.23
α	10°	11°	12°

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